IPC ASSOCIATION CONNEC ELECTRONICS INDUST	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater				eneous Materia	ials and Mfc Information			
upplier Info	rmation													
Company name*			Company unique ID			J	Unique ID Authority				Response Date*			
nsemi											2024-05-16			
Contact Name		Title - Contact			F	Phone - Contact*				Email - Contact*				
Product-Env-Ste	ewards	Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com				
uthorized Repr	esentative*	Title - Representative			F	Phone - Representative*			Email - Representative*					
Product-Env-Ste	ewards	Product Enviro Compliance			]	NA				Product-Env-Stewards@onsemi.com				
Reque	ester Item Number	Mfr Item	Number	Mfr Item Name			Effective Date	Version	Manufac	Manufacturing Site		eight*	UOM	Unit Type
		FOD4108SV		6PB ZC SNUB SMD VDE			2024-05-16 THH			53	7.109	mg	Each	
T	ng Process Informa		orminal Daga	Alloy	STD-020 MSL	Dating	Dook Proces	ng Pody Town	aratura May	Time at Deals	Tomporatus	Numb	er of Reflow Cyc	Jac
1		Terminal Base Alloy J-STD-020 CU Alloy 1		S1D-020 MSL	. Kating	Peak Process Body Temperatu 260 C						er of Reflow Cyc	ries	
	1111 (511) - annealed		U Alloy	1			200	C	[30		seconds	3		
omments	n time at peak temperat	uro durina col	doring is 10.3	0 seconds										
	n time at peak temperat ation regarding materia													

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level Substance		CAS	Exempt	Weight	Unit of Measure
Coupling Gel	1.83	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		0.635	mg
			Supplier	Dimethyl Siloxane	68083-19-2		0.888	mg
			Supplier	3-Methacryloxypropyltrimethoxysilane (C10H20O5Si)	2530-85-0		0.307	mg
Die	4.043	mg	В	Gallium Arsenide (AsGa)	1303-00-0		0.283	mg
			Supplier	Silicon (Si)	7440-21-3		3.76	mg
Die Attach	1.665	mg	Supplier	Silver (Ag)	7440-22-4		1.2487	mg
			Supplier	Phenolic Resin-2	54208-63-8		0.4162	mg
Lead Frame	108.322	mg	Supplier	Silver (Ag)	7440-22-4		0.68	mg
			Supplier	Zinc (Zn)	7440-66-6		0.13	mg
			Supplier	Iron (Fe)	7439-89-6		2.48	mg
			Supplier	Copper (Cu)	7440-50-8		105	mg
			Supplier	Phosphorus (P)	7723-14-0		0.032	mg
Mold Compound-Black	414.4	mg	Supplier	2,6-dibromo-4-[1-(3-bromo-4-hydroxyphenyl)-1-methylethyl]phenol	6386-73-8		16.6	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		95.3998	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		12.4	mg
			Supplier	Carbon Black (C)	1333-86-4		4.15	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		285.8498	mg
Plating	6.7	mg	Supplier	Tin (Sn)	7440-31-5		6.7	mg
Wire Bond - Au	0.149	mg	Supplier	Gold (Au)	7440-57-5		0.149	mg